

AMENDMENTS TO THE SPECIFICATION

Before line 3 on page 1, insert:

Background of the Invention

Replace the first paragraph on page 1 with the following paragraph:

The invention relates to a handling device for wafers (semiconductor disks) or other disk-like substrates, which has a storage device in which a plurality of wafers can be arranged with their surfaces aligned substantially parallel to one another, one behind another and outside a transport container, and is provided with a gripping device with which individual wafers can be removed from the storage device and/or inserted into it. The invention additionally relates to a gripping device, a storage device and a method ~~according to the preambles of claims 9, 10 and 12.~~

After line 12 on page 2a, insert:

Summary of the Invention

Replace the last paragraph beginning on page 5 with the following paragraph:

A further aspect of the invention relates to a method of assembling a wafer batch ~~as indicated in claims 12 or 13.~~ In the case of previously known methods, provision is made that, in one cycle, firstly in each case a wafer is removed by an individual gripper from a wafer stack arranged in a storage device and is arranged in a holding device. This cycle is repeated with other wafers, always using the same gripper, until the wafer batch has been assembled. Turning away from this, in a method according to the invention, provision can be made that firstly a plurality of wafers, preferably a complete wafer batch, is removed from the initial wafer stack one after another by a gripping device. Only after a plurality of wafers have been removed one after another by the gripping device are the wafers passed on by the gripping device, preferably simultaneously, to the storage device or to a holding device differing from the latter.

After line 31 on page 6, insert:

Brief Description of the Drawings

After line 26 on page 7, insert:

Detailed Description of the Invention